

**WHAT IS CLAIMED IS:**

1. A processing apparatus that processes a wafer on which a device is formed in each of a plurality of regions marked out by a plurality of planned dividing lines set on a front surface side, the processing apparatus comprising:

a cassette table on which a cassette that houses a plurality of wafers is placed;

a chuck table that holds the wafer carried out from the cassette placed on the cassette table;

a processing unit that executes processing for a region corresponding to the planned dividing line of the wafer held by the chuck table;

a processing feed unit that executes processing feed of the chuck table and the processing unit relatively;

an imaging unit that images the wafer held by the chuck table; and

a control unit that controls the processing unit, the processing feed unit, and the imaging unit, wherein

the control unit includes

a control section that positions the chuck table directly under the imaging unit by actuating the processing feed unit to relatively move the chuck table

and causes the imaging unit to image the wafer after the processing unit has processed regions corresponding to all of the planned dividing lines of the wafer held by the chuck table, and

a report creating section that derives information relating to a processing state in each area on a basis of images obtained by individually imaging two or more different areas in the regions corresponding to all of the planned dividing lines along which the processing has been executed and creates a report in which the information and the images are recorded,

wherein

the information relating to the processing state includes width of a groove formed in the region corresponding to the planned dividing line, a state of a defect formed at the groove, and an amount of deviation of the groove from a center line of the planned dividing line.

2. The processing apparatus according to claim 1, wherein

the report creating section creates the report for the wafer for which the processing has been executed first in the plurality of wafers housed in the cassette.

~~3. The processing apparatus according to claim 1,~~

wherein

~~the information relating to the processing state includes width of a groove formed in the region corresponding to the planned dividing line, a state of a defect formed at the groove, and an amount of deviation of the groove from a center line of the planned dividing line.~~

34. The processing apparatus according to claim 1, further comprising:

a display unit that displays content of the report.

45. The processing apparatus according to claim 1, wherein

the control unit further includes an arrangement deciding section that decides an arrangement of the two or more different areas if the number of the two or more different areas imaged by the imaging unit is specified.

56. The processing apparatus according to claim 1, wherein

the processing unit is either a cutting unit including a cutting blade rotatably or a laser beam irradiation unit including a light collector that collects a laser beam.

6. The processing apparatus according to claim 4, wherein

the arrangement deciding section sets coordinates of an intersection of the center line of the planned dividing line of a horizontal direction and the center line of the planned dividing line of a vertical direction as center coordinates of each of predefined two or more inspection regions of the wafer individually imaged by the imaging unit.

7. The processing apparatus according to claim 6, wherein

the wafer has a circular disc shape,  
one or a plurality of the predefined two or more inspection regions located at an end part of the wafer is located outside relative to a circumference of the front surface side of the wafer if plural inspection regions are disposed at equal intervals in the horizontal direction and the vertical direction, and

the arrangement deciding section corrects the coordinates of the one or plurality of inspection regions in such a manner that the one or plurality of inspection regions at the end part are located inside relative to the circumference of the front surface side of the wafer.